

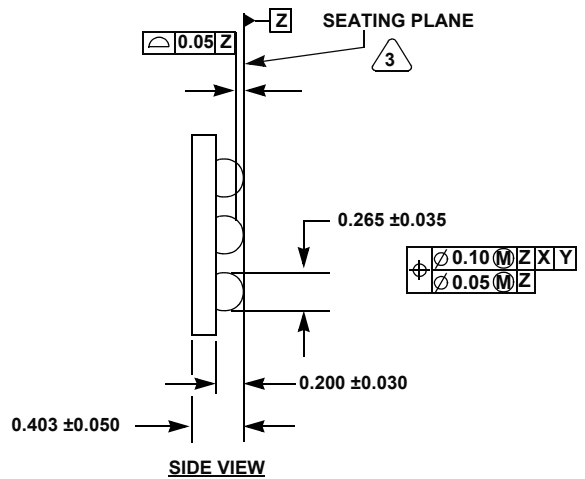
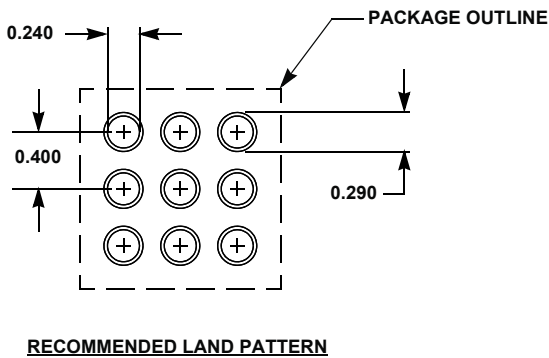
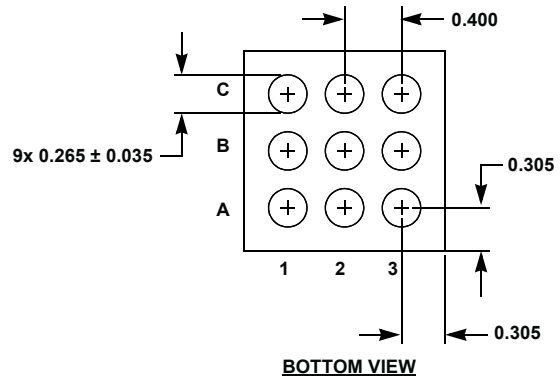
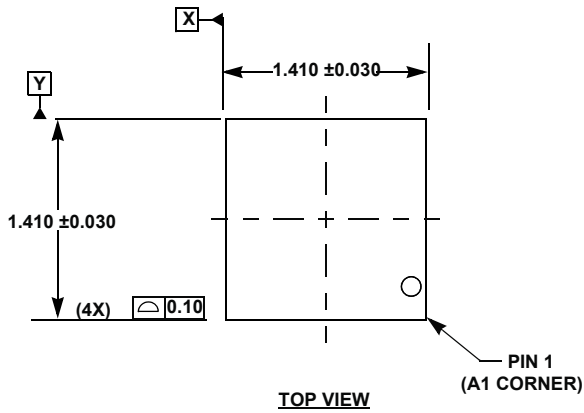
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### W3x3.9F

9 BALL 3x3 ARRAY THIN WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)

Rev 0, 3/16



#### NOTES:

1. All dimensions are in millimeters.

② Dimensions and tolerance per ASMEY 14.5 - 1994, and JESD 95-1 SPP-010.

③ NSMD refers to non-solder mask defined pad design per [TB451](#).